

Amendments to the Claims:

Please amend claims 24, 25, and 29-31 as follows. Following is a complete listing of the claims pending in the application, as amended:

1-23. (Cancelled)

24. (Currently Amended) A method for forming a textured planarizing pad, comprising:

floating a film of a support material on a supporting liquid;

separating a planarizing pad material into discrete elements;

distributing the discrete elements in and/or on the support material floated on the supporting liquid; and

drawing the support material and the discrete elements from the supporting liquid by engaging the support material with a backing material and moving the backing material away from the liquid.

25. (Currently Amended) The method of claim 24, further comprising separating the planarizing pad material into discrete elements and mixing the discrete elements with the support material before disposing the support material on the a surface of the supporting liquid.

26. (Original) The method of claim 24, further comprising selecting the support material to include an organic Langmuir-Blodgett film material.

27. (Original) The method of claim 24, further comprising selecting the supporting liquid to include water.

28. (Original) The method of claim 24, further comprising disposing the discrete elements onto the support material after disposing the support material on the liquid.

29. (Currently Amended) The method of claim 24, further comprising disposing the support material on the-a surface of the supporting liquid to a thickness of one molecule.

30. (Withdrawn and Currently Amended) A method for removing material from a microelectronic substrate, comprising:

forming a planarizing pad by floating a film of a first support material on a supporting liquid, separating a planarizing pad material into discrete elements, distributing the discrete elements in and/or on the support material floated on the supporting liquid, and drawing the support material and the discrete elements from the supporting liquid by engaging the support material with a backing material and moving the backing material away from the liquid;
engaging the planarizing pad with the microelectronic substrate; and
moving at least one of the planarizing pad and the microelectronic substrate relative to the other to remove material from the microelectronic substrate.

31. (Withdrawn and Currently Amended) The method of claim 30, further comprising separating the planarizing pad material into discrete elements and mixing the discrete elements with the support material before disposing the support material on the-a surface of the support liquid.

32. (Withdrawn) The method of claim 30, further comprising selecting the support material to include an organic Langmuir-Blodgett film material.

33. (Withdrawn) The method of claim 30, further comprising disposing the discrete elements onto the support material after disposing the support material on the liquid.

34. (Withdrawn) The method of claim 30, further comprising disposing a planarizing liquid between a planarizing surface of the planarizing pad and a surface of the microelectronic substrate.

35-54. (Canceled)